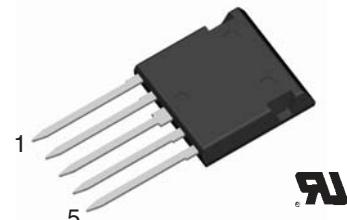
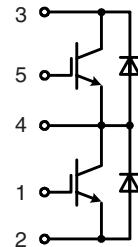


NPT³ IGBT

Phaseleg Topology
in ISOPLUS i4-PACTM

I_{C25} = 33 A
V_{CES} = 1200 V
V_{CE(sat) typ} = 2.4 V

**IGBTs**

Symbol	Conditions	Maximum Ratings		
V _{CES}	T _{VJ} = 25°C to 150°C	1200		V
V _{GES}		± 20		V
I _{C25}	T _C = 25°C	33		A
I _{C90}	T _C = 90°C	20		A
I _{CM}	V _{GE} = ±15 V; R _G = 68 Ω; T _{VJ} = 125°C RBSOA, Clamped inductive load; L = 100 μH	40		A
V _{CEK}		V _{CES}		
t _{sc} (SCSOA)	V _{CE} = 900V; V _{GE} = ±15 V; R _G = 68 Ω; T _{VJ} = 125°C non-repetitive	10		μs
P _{tot}	T _C = 25°C	150		W

Symbol	Conditions	Characteristic Values		
		(T _{VJ} = 25°C, unless otherwise specified)	min.	typ.
V _{CE(sat)}	I _C = 20 A; V _{GE} = 15 V; T _{VJ} = 25°C T _{VJ} = 125°C	2.4 2.8	2.9 V	V
V _{GE(th)}	I _C = 0.6 mA; V _{GE} = V _{CE}	4.5	6.5	V
I _{CES}	V _{CE} = V _{CES} ; V _{GE} = 0 V; T _{VJ} = 25°C T _{VJ} = 125°C	0.2	0.2	mA mA
I _{GES}	V _{CE} = 0 V; V _{GE} = ± 20 V		200	nA
t _{d(on)} t _r t _{d(off)} t _f E _{on} E _{off}	Inductive load, T _{VJ} = 125°C V _{CE} = 600 V; I _C = 20 A V _{GE} = ±15 V; R _G = 68 Ω	205 105 320 175 4.1 1.5	ns ns ns ns mJ mJ	
C _{ies}		1.2	nF	
Q _{Gon}		100	nC	
R _{thJC}			0.8	K/W
R _{thJH}	with heat transfer paste	1.2		K/W

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Diodes

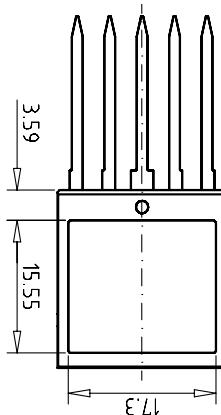
Symbol	Conditions	Maximum Ratings		
I_{F25}	$T_C = 25^\circ C$	25	A	
I_{F90}	$T_C = 90^\circ C$	15	A	

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
V_F	$I_F = 20 A; T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	2.5 1.9	3.0 V	V
I_{RM} t_{rr}	$\left. \begin{array}{l} I_F = 15 A; dI_F/dt = -400 A/\mu s; T_{VJ} = 125^\circ C \\ V_R = 600 V; V_{GE} = 0 V \end{array} \right\}$	16 130	A ns	
R_{thJC} R_{thCH}	(per diode) with heat transfer paste	3.6	2.3 K/W K/W	

Component

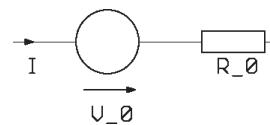
Symbol	Conditions	Maximum Ratings		
T_{VJ}		-55...+150	$^\circ C$	
T_{stg}		-55...+125	$^\circ C$	
V_{ISOL}	$I_{ISOL} \leq 1 mA; 50/60 Hz$	2500	V~	
F_c	mounting force with clip	20...120	N	

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
C_p	coupling capacity between shorted pins and mounting tab in the case	40	pF	
d_s, d_A	pin - pin	1.7		mm
d_s, d_A	pin - backside metal	5.5		mm
Weight		9		g



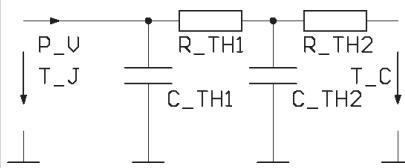
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Equivalent Circuits for Simulation**Conduction**

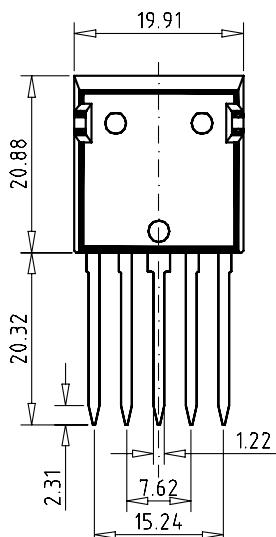
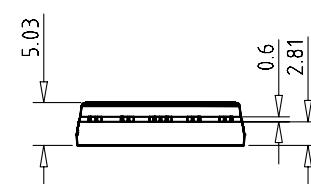
IGBT (typ. at $V_{GE} = 15 V; T_J = 125^\circ C$)
 $V_o = 1.09 V; R_o = 85 m\Omega$

Free Wheeling Diode (typ. at $T_J = 125^\circ C$)
 $V_o = 1.3 V; R_o = 32 m\Omega$

Thermal Response

IGBT (typ.)
 $C_{th1} = 0.049 J/K; R_{th1} = 0.15 K/W$
 $C_{th2} = 0.133 J/K; R_{th2} = 0.65 K/W$

Free Wheeling Diode (typ.)
 $C_{th1} = 0.021 J/K; R_{th1} = 0.63 K/W$
 $C_{th2} = 0.052 J/K; R_{th2} = 1.67 K/W$

Dimensions in mm (1 mm = 0.0394")

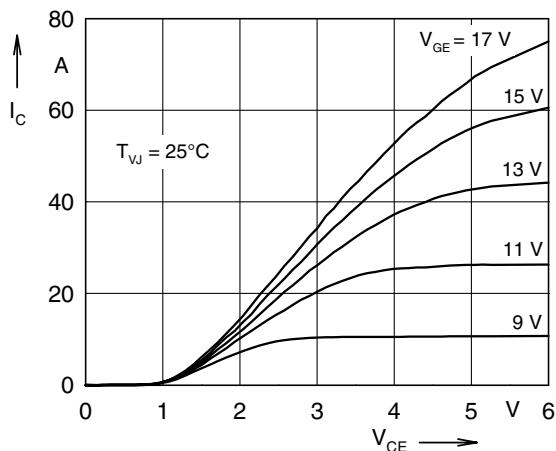


Fig. 1 Typ. output characteristics

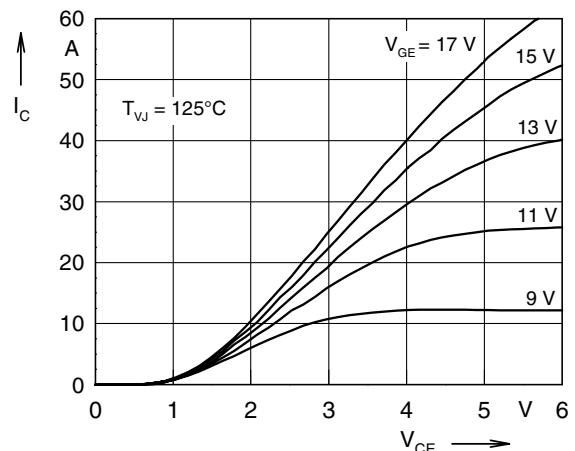


Fig. 2 Typ. output characteristics

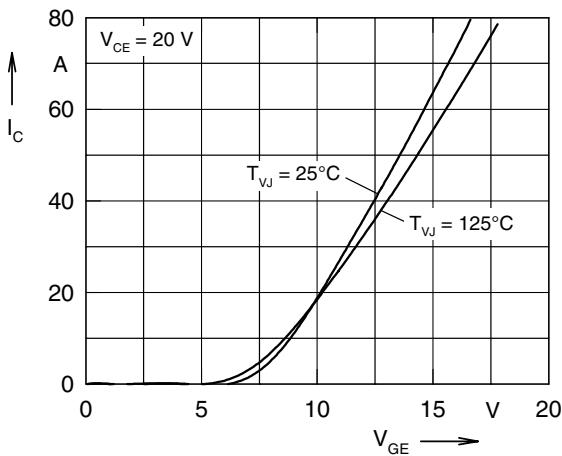


Fig. 3 Typ. transfer characteristics

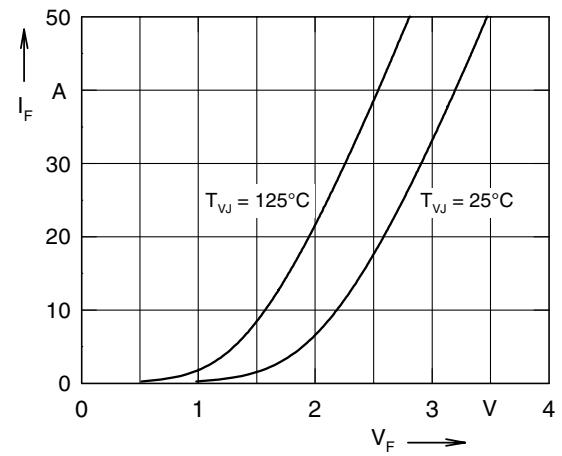


Fig. 4 Typ. forward characteristics of free wheeling diode

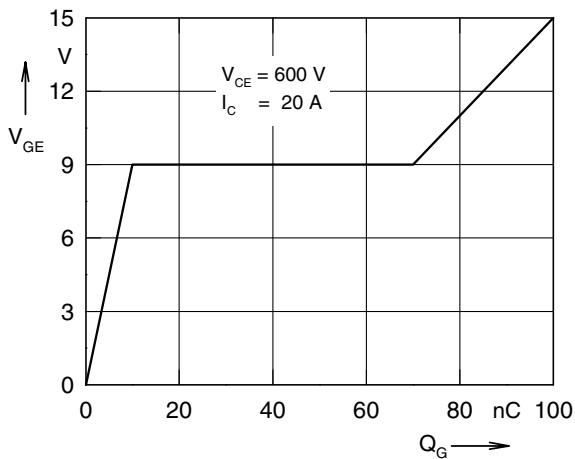


Fig. 5 Typ. turn on gate charge

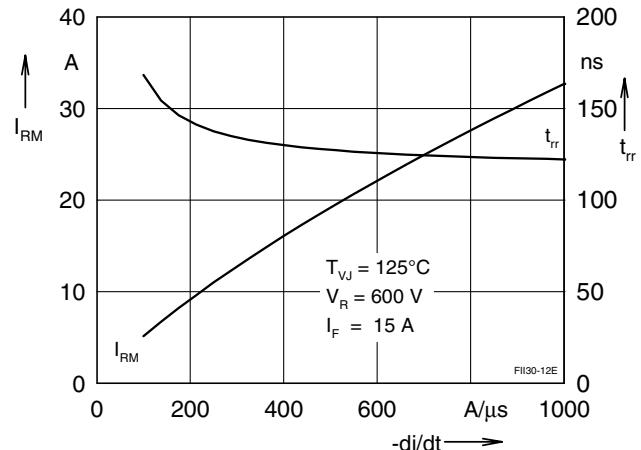


Fig. 6 Typ. turn off characteristics of free wheeling diode

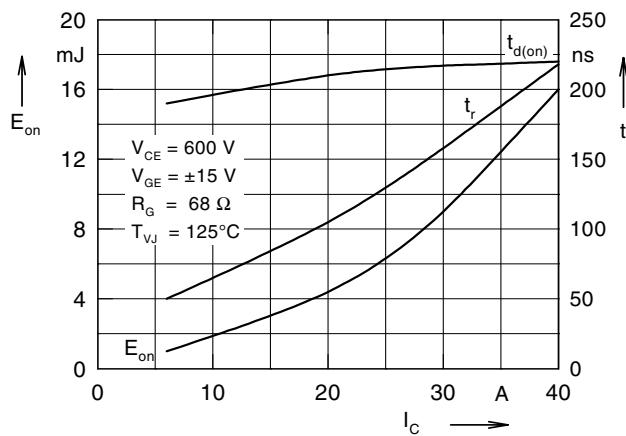


Fig. 7 Typ. turn on energy and switching times versus collector current

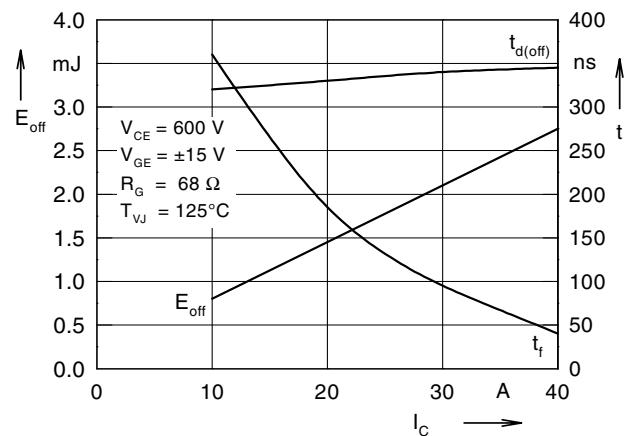


Fig. 8 Typ. turn off energy and switching times versus collector current

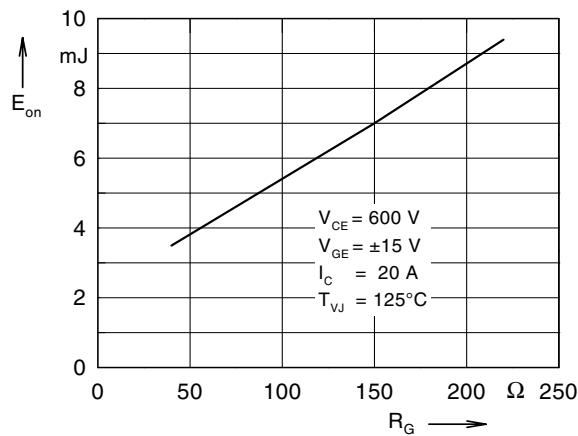


Fig. 9 Typ. turn on energy vs gate resistor

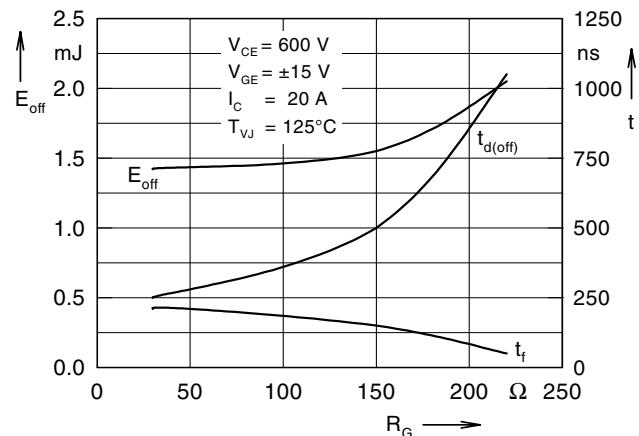


Fig. 10 Typ. turn off energy and switching times versus gate resistor

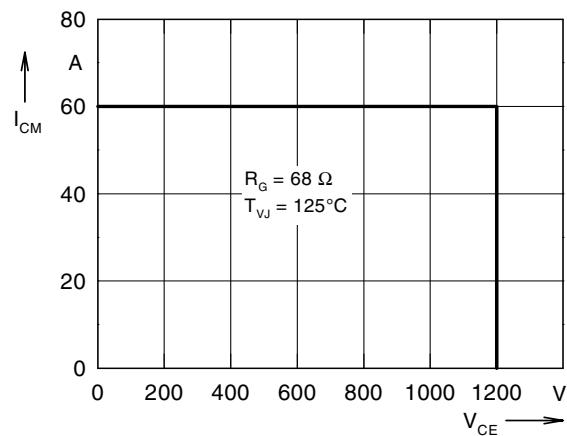


Fig. 11 Reverse biased safe operating area RBSOA

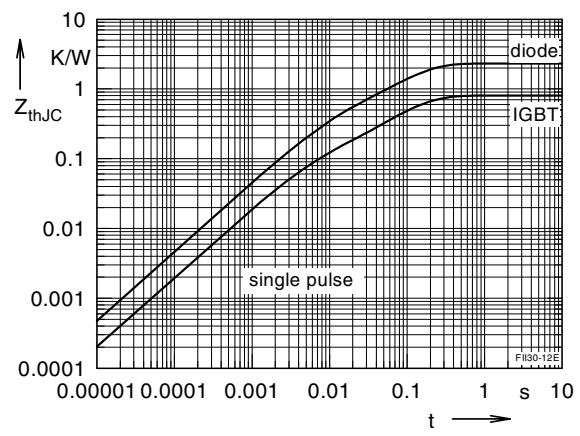


Fig. 12 Typ. transient thermal impedance